

# MBRF2545CT

Preferred Device

## SWITCHMODE™ Schottky Power Rectifier

The SWITCHMODE Power Rectifier employs the Schottky Barrier principle in a large area metal-to-silicon power diode. State-of-the-art geometry features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for use as rectifiers in very low-voltage, high-frequency switching power supplies, free wheeling diodes and polarity protection diodes.

### Features

- Highly Stable Oxide Passivated Junction
- Very Low Forward Voltage Drop
- Matched Dual Die Construction
- High Junction Temperature Capability
- High dv/dt Capability
- Excellent Ability to Withstand Reverse Avalanche Energy Transients
- Guardring for Stress Protection
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Electrically Isolated
- No Isolation Hardware Required
- Pb-Free Package is Available\*

### Mechanical Characteristics:

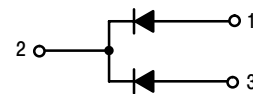
- Case: Epoxy, Molded
- Weight: 1.9 Grams (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead Temperature for Soldering Purposes:  
260°C Max. for 10 Seconds



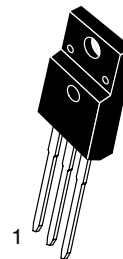
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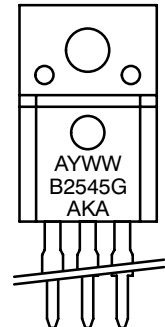
## SCHOTTKY BARRIER RECTIFIER 25 AMPERES, 45 VOLTS



### MARKING DIAGRAM



ISOLATED TO-220  
CASE 221D  
STYLE 3



A = Assembly Location  
Y = Year  
WW = Work Week  
B2545 = Device Code  
G = Pb-Free Package  
AKA = Diode Polarity

### ORDERING INFORMATION

Device	Package	Shipping
MBRF2545CT	TO-220	50 Units/Rail
MBRF2545CTG	TO-220 (Pb-Free)	50 Units/Rail

**Preferred** devices are recommended choices for future use and best overall value.

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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## MAXIMUM RATINGS (Per Leg)

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	$V_{RRM}$ $V_{RWM}$ $V_R$	45	V
Average Rectified Forward Current (Rated $V_R$ ), $T_C = 125^\circ\text{C}$	$I_{F(AV)}$	12.5 25	A
Peak Repetitive Forward Current (Rated $V_R$ , Square Wave, 20 kHz), $T_C = 125^\circ\text{C}$	$I_{FRM}$	25	A
Non-repetitive Peak Surge Current (Surge applied at rated load conditions halfwave, single phase, 60 Hz)	$I_{FSM}$	150	A
Peak Repetitive Reverse Surge Current (2.0 $\mu\text{s}$ , 1.0 kHz)	$I_{RRM}$	1.0	A
Operating Junction and Storage Temperature (Note 1)	$T_J, T_{stg}$	- 65 to +175	$^\circ\text{C}$
Voltage Rate of Change (Rated $V_R$ )	$dv/dt$	10000	V/ $\mu\text{s}$
RMS Isolation Voltage (t = 0.3 second, R.H. $\leq$ 30%, $T_A = 25^\circ\text{C}$ ) (Note 2)	$V_{iso1}$	4500	V

## THERMAL CHARACTERISTICS (Per Leg)

Maximum Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	3.5	$^\circ\text{C}/\text{W}$
Maximum Lead Temperature for Soldering Purposes: 1/8" from Case for 5 Seconds	$T_L$	260	$^\circ\text{C}$

## ELECTRICAL CHARACTERISTICS (Per Leg)

Characteristic	Symbol	Max	Unit
Maximum Instantaneous Forward Voltage (Note 3) ( $i_F = 12.5$ A, $T_C = 25^\circ\text{C}$ ) ( $i_F = 12.5$ A, $T_C = 125^\circ\text{C}$ )	$v_F$	0.7 0.62	V
Maximum Instantaneous Reverse Current (Note 3) (Rated DC Voltage, $T_C = 25^\circ\text{C}$ ) (Rated DC Voltage, $T_C = 125^\circ\text{C}$ )	$i_R$	0.2 40	mA

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. The heat generated must be less than the thermal conductivity from Junction-to-Ambient:  $dP_D/dT_J < 1/R_{\theta JA}$ .
2. Proper strike and creepage distance must be provided.
3. Pulse Test: Pulse Width = 300  $\mu\text{s}$ , Duty Cycle  $\leq$  2.0%.

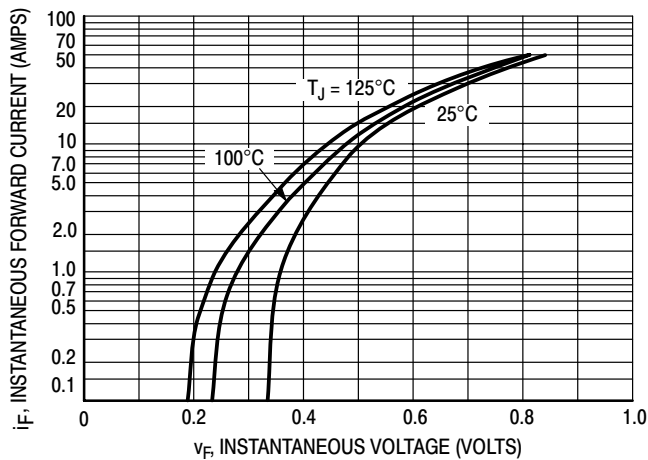


Figure 1. Typical Forward Voltage, Per Leg

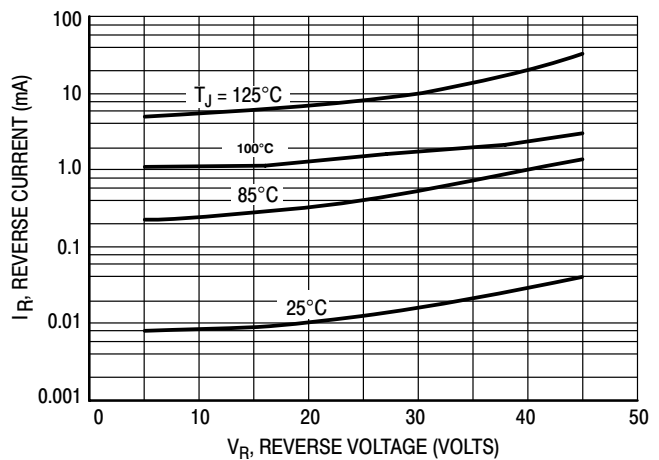


Figure 2. Typical Reverse Current, Per Leg

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## TEST CONDITIONS FOR ISOLATION TEST\*

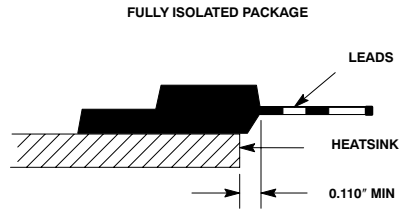
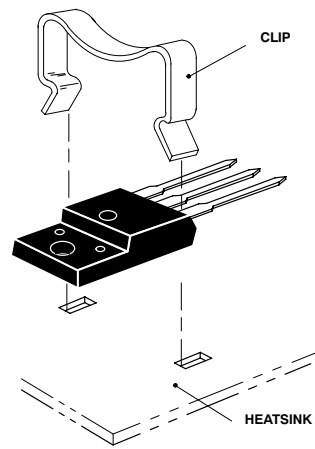


Figure 3. Mounting Position

\* Measurement made between leads and heatsink with all leads shorted together.

## MOUNTING INFORMATION



Clip-Mounted

Figure 4. Typical Mounting Technique

